AMENDMENTS

In The Claims:

Please amend the claims as follows:

Claims 1-11 (cancelled)

Claim12. (currently amended) A flip-chip light emitting diode package structure, comprising:

a submount having a first surface and a second surface opposite to the first surface, an indentation on the first surface, a plurality of grooves on a first sidewall and a second sidewall of the submount;

a first patterned conductive reflection film disposed on a first part of the first surface, a first part of the second surface, a first part of a sidewall of the indention, a first part of a bottom of the indentation and a part of an inner wall of the grooves;

a second patterned conductive reflection film on a second part of the first surface, a second part of the second surface, a second part of the sidewall of the indention and a second part of the bottom of the indentation, and a remaining part of the inner wall of the grooves; and

~~at least two~~a light emitting diode (LED) chip~~chips~~ inside the indentation of the submount, wherein ~~each of~~ the LED chip~~chips~~ has two electrodes electrically connecting with the first patterned conductive reflection film and the second patterned conductive reflection film, respectively,

~~wherein at least one of the first patterned conductive film and the second patterned conductive film is commonly used by the LED chips;~~

wherein no integrated circuit (IC) chip is connected to the first patterned conductive reflection film and the second patterned conductive reflection film.

Claim 13. (original) The flip-chip light emitting diode package structure of claim 12, further comprising two bumps disposed between the electrodes of the LED chip, and the first patterned conductive reflection film and the second patterned conductive reflection film.

Claim 14. (previously presented) The flip-chip light emitting diode package structure of claim 12, wherein m is a number of the grooves that are on the first sidewall of the submount and n is a number of the grooves that are on the second sidewall of the submount, wherein at least one of m and n is greater than or equal to two.

Claim 15. (original) The flip-chip light emitting diode package structure of claim 14, wherein the first and the second sidewalls are next to each other.

Claim 16. (original) The flip-chip light emitting diode package structure of claim 14, wherein the first and the second sidewalls are opposite to each other.

Claim 17. (original) The flip-chip light emitting diode package structure of claim 14, wherein m is not equal to n.

Claim 18. (original) The flip-chip light emitting diode package structure of claim 14, wherein m is equal to n.

Claim 19. (original) The flip-chip light emitting diode package structure of claim 14, wherein m is 1 and n is 1.

Claim 20. (original) The flip-chip light emitting diode package structure of claim 12, wherein the grooves are disposed on a sidewall at a corner of the submount.

Claim 21. (previously presented) The flip-chip light emitting diode package structure of claim 13, wherein the bumps comprise a Sn-Pb alloy, a Sn-Au alloy or Au.

Claim 22. (original) The flip-chip light emitting diode package structure of claim 12, wherein the submount comprises a material selected from the group consisting of aluminum nitride, boron nitride or zinc oxide.

Claim 23. (original) The flip-chip light emitting diode package structure of claim 12, wherein an angle formed between the sidewall and the bottom of the indentation is an obtuse angle.

Claims 24-26 (cancelled)

Claim 27. (previously presented) The flip-chip light emitting diode package structure of claim 12, wherein at least one of m and n is greater than 1.